

Title (en)

Cooling apparatus for integrated circuit chips.

Title (de)

Kühlapparat für integrierte Schaltungs chips.

Title (fr)

Dispositif de refroidissement pour des puces à circuit intégré.

Publication

EP 0630046 A2 19941221 (EN)

Application

EP 94109507 A 19940620

Priority

JP 14874093 A 19930621

Abstract (en)

A cooling apparatus for integrated circuit chips (112) in which the pressure of coolant does not affect the chips (112) is disclosed. A block (121) is provided with a plurality of holes. Cooling members (131) are inserted in these holes. An elastic member (134) is filled between the block (121) and the cooling member (131). The cooling member (131) is supported to the block (121) by the elastic member (134). Each cooling member (131) is connected to each other by pipes (132). A bellows (133) can be provided between the cooling member (131) and the pipe (132). When the block (121) is loaded on the substrate (111) on which the integrated circuit chips (112) are mounted, the elastic member (134) deforms and the cooling member (131) displaces in accordance with the height and inclination of the integrated circuit chip (112). The lower surface of the cooling member (131) is brought into close contact with the integrated circuit chip (112) due to the deformation of the elastic member (134). The bellows (133) deforms in accordance with the displacement of the cooling member (131) to ensure the normal connection of the pipe (132). When the coolant is supplied, the expanded bellows (133) pushes the pipe (132) up but does not push the cooling member (131) down. <IMAGE>

IPC 1-7

H01L 23/433; **H01L 23/473**

IPC 8 full level

H01L 23/433 (2006.01); **H01L 23/473** (2006.01)

CPC (source: EP US)

H01L 23/433 (2013.01 - EP US); **H01L 23/4735** (2013.01 - EP US); **H01L 2224/16** (2013.01 - EP US)

Designated contracting state (EPC)

DE FR GB

DOCDB simple family (publication)

EP 0630046 A2 19941221; **EP 0630046 A3 19950517**; **EP 0630046 B1 20020227**; CA 2126291 A1 19941222; CA 2126291 C 19981013; DE 69429949 D1 20020404; DE 69429949 T2 20020627; JP 2500757 B2 19960529; JP H07142656 A 19950602; US 5465192 A 19951107

DOCDB simple family (application)

EP 94109507 A 19940620; CA 2126291 A 19940620; DE 69429949 T 19940620; JP 14874093 A 19930621; US 26337794 A 19940621